



Product Change Notification: DSN0-23HXZH038

Date:

13-Jul-2026

Product Category:

32-Bit Microcontrollers

Notification Subject:

CCB 7437 Final Notice: Qualification of ATP7 as an additional assembly site for ATSAM3S4CA-CU, ATSAM3S4CA-CUR, ATSAM3S2CA-CU, ATSAM3S2CA-CUR, ATSAM3N0CA-CU, ATSAM3N0CA-CUR, ATSAM3SD8CA-CU, ATSAM3SD8CA-CUR, ATSAM3S8CA-CU, ATSAM3S8CA-CUR, ATSAM3U1CB-CU, ATSAM3N1CB-CU, ATSAM3N1CB-CUR catalog part numbers (CPN) available in 100L TFBGA (9x9x1.2mm) package.

Affected CPNs:

[DSNO-23HXZH038_Affected_CPN_07132026.pdf](#)

[DSNO-23HXZH038_Affected_CPN_07132026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ATP7 as an additional assembly site for ATSAM3S4CA-CU, ATSAM3S4CA-CUR, ATSAM3S2CA-CU, ATSAM3S2CA-CUR, ATSAM3N0CA-CU, ATSAM3N0CA-CUR, ATSAM3SD8CA-CU, ATSAM3SD8CA-CUR, ATSAM3S8CA-CU, ATSAM3S8CA-CUR, ATSAM3U1CB-CU, ATSAM3N1CB-CU, ATSAM3N1CB-CUR catalog part numbers (CPN) available in 100L TFBGA (9x9x1.2mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 27, 2025: Issued initial notification.

July 13, 2026: Issued final notification. Updated the Core Material for the ASSH site in the post change section of the Pre and Post Change Summary table from "HL832NS" to "HL832NX." Added a 'Change (Yes/No)' column to the Pre and Post Change Summary table. Attached the Qualification Report. Provided estimated first ship date to be on August 21, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-23HXZH038 Qual Report.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

ATSAM3N1CB-CUR

ATSAM3S4CA-CU

ATSAM3S4CA-CUR

ATSAM3S2CA-CU

ATSAM3S2CA-CUR

ATSAM3N0CA-CU

ATSAM3N0CA-CUR

ATSAM3SD8CA-CU

ATSAM3SD8CA-CUR

ATSAM3S8CA-CU

ATSAM3S8CA-CUR

ATSAM3U1CB-CU

ATSAM3N1CB-CU



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: DSNO-23HXZH038

Date: June 29, 2026

Qualification of ATP7 as an additional assembly site for ATSAM3S4CA-CU, ATSAM3S4CA-CUR, ATSAM3S2CA-CU, ATSAM3S2CA-CUR, ATSAM3N0CA-CU, ATSAM3N0CA-CUR, ATSAM3SD8CA-CU, ATSAM3SD8CA-CUR, ATSAM3S8CA-CU, ATSAM3S8CA-CUR, ATSAM3U1CB-CU, ATSAM3N1CB-CU, ATSAM3N1CB-CUR catalog part numbers (CPN) available in 100L TFBGA (9x9x1.2mm) package.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of ATP7 as an additional assembly site for ATSAM3S4CA-CU, ATSAM3S4CA-CUR, ATSAM3S2CA-CU, ATSAM3S2CA-CUR, ATSAM3N0CA-CU, ATSAM3N0CA-CUR, ATSAM3SD8CA-CU, ATSAM3SD8CA-CUR, ATSAM3S8CA-CU, ATSAM3S8CA-CUR, ATSAM3U1CB-CU, ATSAM3N1CB-CU, ATSAM3N1CB-CUR catalog part numbers (CPN) available in 100L TFBGA (9x9x1.2mm) package.

QUAL ID:	REQ2500790 Rev. A
MP CODE:	58U837CQBC01
Part No.:	ATSAM3S8CA-CU
CCB No.:	7437

Substrate

Core Material:	HL832NS
Core Thickness:	0.1 mm
L1/L2 Thickness	0.018 mm MIN.
SM Material:	AUS308
Process	STD. Bussed
SM Thickness:	0.03mm
Part Number:	101430765
Drill Size:	0.2mm
Line/Space Specs:	0.045/0.045 mm

Bond Wire

Wire:	Au wire
--------------	---------

Die Attach Material

Epoxy:	2300
---------------	------

Mold Compound

Mold Compound:	G770FE
-----------------------	--------

Package

Type:	TFBGA
Pin/Ball Count:	100
Package Size:	9x9x1.2mm

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.
ATP7260600001.000
ATP7260600002.000
ATP7260600003.000

Result: **Pass**

Conclusion:

58U83 UMC 0.15um in 100L TFBGA 9x9x1.2mm Au wire at ATP7 is qualified for Moisture/Reflow Sensitivity Classification Level 3 at 260°C reflow temperature as per IPC/JEDEC J-STD-020E standard and is Passed in qualification requirements.

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Moisture Soak Precondition Prior to Stresses	MSL 3: 150C 24-hour Bake, 192-hour moisture soak at 65°C / 85%RH. 3x Reflow at 260°C max. Electrical test at 25°C and 85°C	JESD22-A113; IPC/JEDEC J-STD-020	231 each lot / 3 lots	Electrical: L1: 0/231, L2: 0/231, L3: 0/231	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
High Temp Storage	150°C / 504 hours Electrical test at 25°C and 85°C	JESD22-A103	45 each lot / 1 Lot	L1: 0/50	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
High Temp Storage	150°C / 1008 hours Electrical test at 25°C and 85°C	JESD22-A103	44 each lot / 1 Lot	L1: 0/45	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Temperature Cycling	-55°C / 125°C Air to Air / 1000 Cycles Electrical test at 85°C	JESD22-A104	77 each lot / 3 lots	Electrical: L1: 0/77, L2: 0/77, L3: 0/77; WBP/WBS: L1: 0/5, n/a, n/a	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Unbiased HAST	+130°C/85% RH / 96 hours (no bias) Electrical test at +25°C	JESD22-A118	77 each lot / 3 lots	L1: 0/77, L2: 0/77, L3: 0/77	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Unbiased HAST	+130°C/85% RH / 192 hours (no bias) Electrical test at +25°C	JESD22-A118	70 each lot / 3 lots	L1: 0/70, L2: 0/70, L3: 0/70	Pass